

# Dual Low-Voltage TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifier

 Ultra Low  $V_F = 0.30\text{ V}$  at  $I_F = 5.0\text{ A}$ 

## eSMP<sup>®</sup> Series SMPD (TO-263AC)



### FEATURES

- Trench MOS Schottky technology
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available:
  - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

### DESIGN SUPPORT TOOLS AVAILABLE



### TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 30 A
$V_{RRM}$	60 V
$I_{FSM}$	320 A
$V_F$ at $I_F = 30\text{ A}$ ( $T_A = 125\text{ °C}$ )	0.50 V
$T_J$ max.	150 °C
Package	SMPD (TO-263AC)
Circuit configuration	Common cathode

### MECHANICAL DATA

**Case:** SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating  
 Base P/N-M3 - halogen-free, RoHS-compliant  
 Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** as marked

MAXIMUM RATINGS ( $T_A = 25\text{ °C}$ unless otherwise noted)			
PARAMETER	SYMBOL	V60D60C	UNIT
Device marking code		V60D60C	
Maximum repetitive peak reverse voltage	$V_{RRM}$	60	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}$ <sup>(1)</sup>	per device	60
		per diode	30
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	320	A
Operating junction temperature range	$T_J$ <sup>(2)</sup>	-40 to +150	°C
Storage temperature range	$T_{STG}$	-55 to +150	

### Notes

(1) Mounted on infinite heatsink

(2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	$I_F = 5\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.41	-	V
	$I_F = 15\text{ A}$			0.48	-	
	$I_F = 30\text{ A}$			0.56	0.64	
	$I_F = 5\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.3	-	
	$I_F = 15\text{ A}$			0.39	-	
	$I_F = 30\text{ A}$			0.5	0.58	
Reverse current per diode	$V_R = 60\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	-	5	mA
		$T_A = 125\text{ }^\circ\text{C}$		30	80	
Typical junction capacitance	4.0 V, 1 MHz		$C_J$	3550	-	pF

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
 (2) Pulse test: Pulse width  $\leq 5\text{ ms}$

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	V60D60C	UNIT
Typical thermal resistance per device	$R_{\theta JC}^{(1)}$	0.8	$^\circ\text{C/W}$
	$R_{\theta JA}^{(2)(3)}$	45	

**Notes**

- (1) Mounted on infinite heatsink  
 (2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$   
 (3) Free air, without heatsink

<b>ORDERING INFORMATION</b> (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V60D60C-M3/I	0.20	I	2000/reel	13" diameter plastic tape and reel
V60D60CHM3/I <sup>(1)</sup>	0.20	I	2000/reel	13" diameter plastic tape and reel

**Note**

- (1) AEC-Q101 qualified

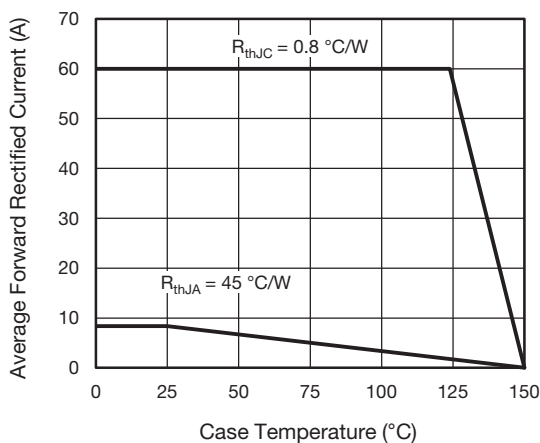
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

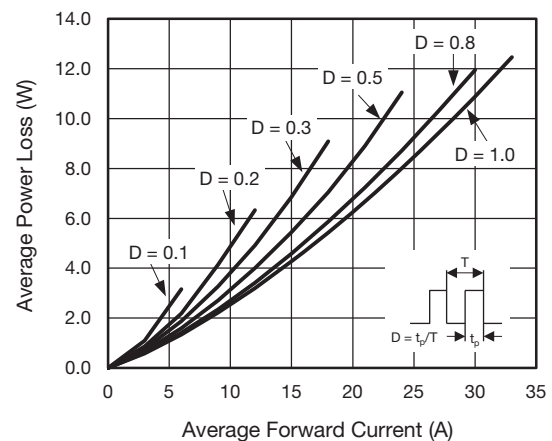


Fig. 2 - Average Power Loss Characteristics

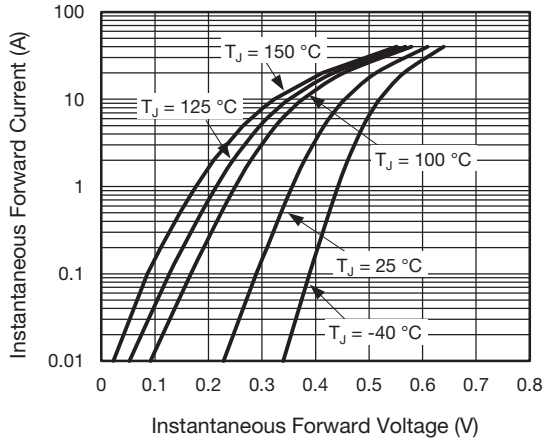


Fig. 3 - Typical Instantaneous Forward Characteristics

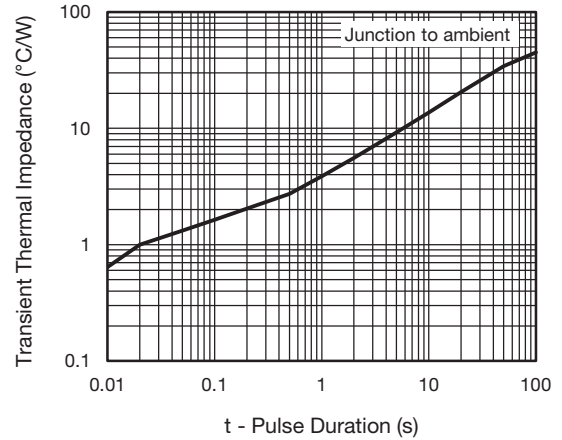


Fig. 6 - Typical Transient Thermal Impedance

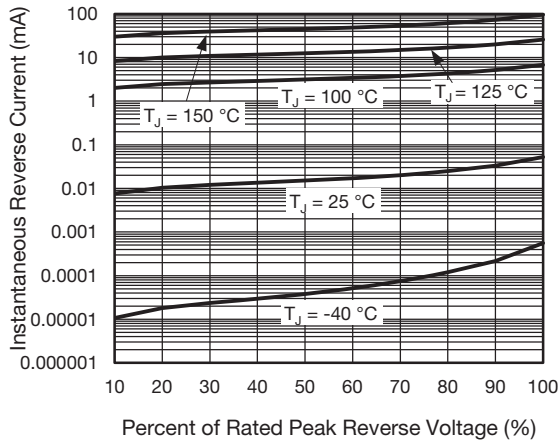


Fig. 4 - Typical Reverse Leakage Characteristics

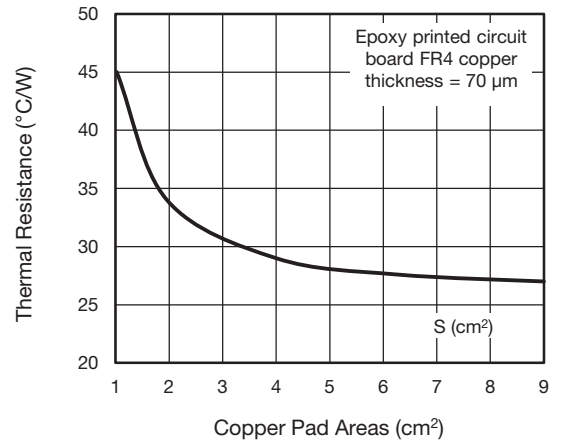


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

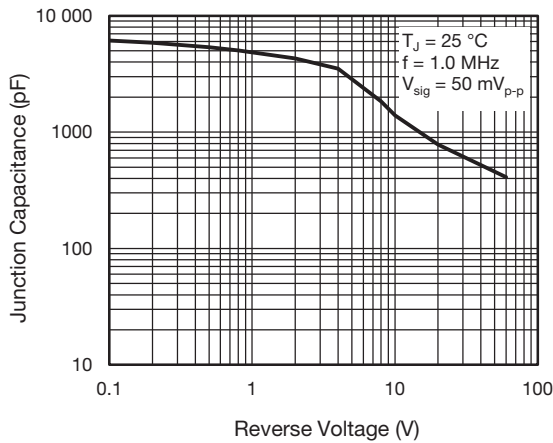
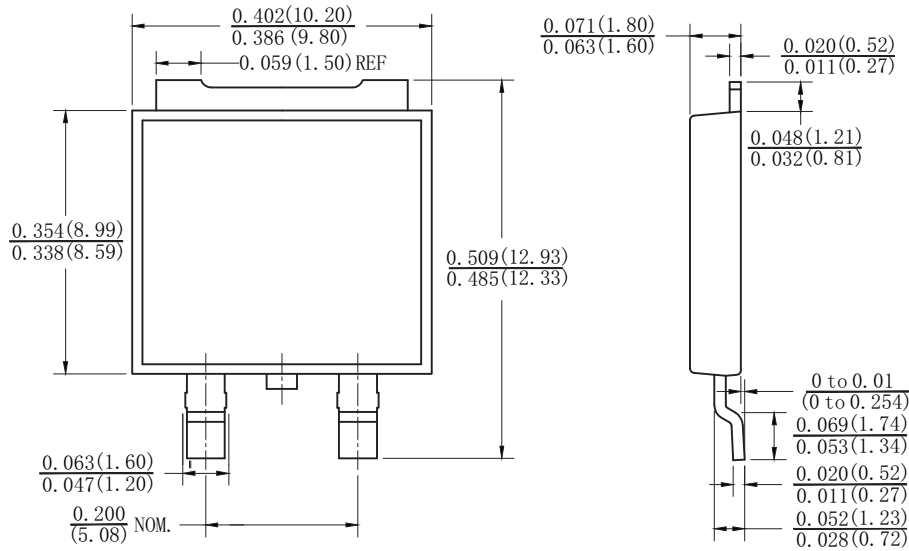


Fig. 5 - Typical Junction Capacitance

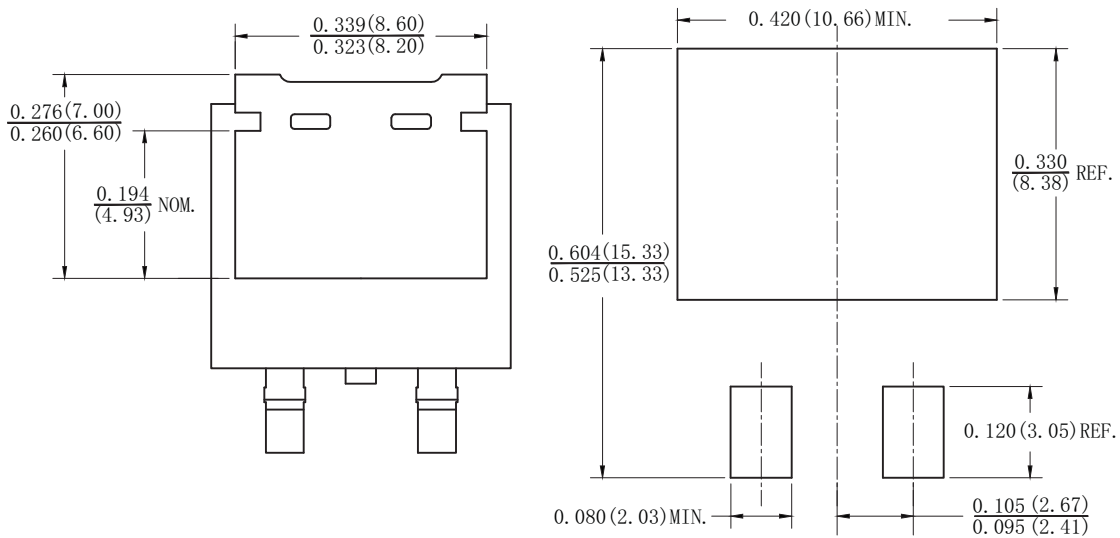


PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SMPD (TO-263AC)



Mounting Pad Layout





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